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Details

Product Status	Active
Number of LABs/CLBs	1920
Number of Logic Elements/Cells	17280
Total RAM Bits	442368
Number of I/O	173
Number of Gates	1000000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s1000-4ftg256i

Table 4: Example Ordering Information

Device	Speed Grade		Package Type/Number of Pins		Temperature Range (T _j)	
XC3S50	-4	Standard Performance	VQ(G)100	100-pin Very Thin Quad Flat Pack (VQFP)	C	Commercial (0°C to 85°C)
XC3S200	-5	High Performance ⁽¹⁾	CP(G)132 ⁽²⁾	132-pin Chip-Scale Package (CSP)	I	Industrial (–40°C to 100°C)
XC3S400			TQ(G)144	144-pin Thin Quad Flat Pack (TQFP)		
XC3S1000			PQ(G)208	208-pin Plastic Quad Flat Pack (PQFP)		
XC3S1500			FT(G)256	256-ball Fine-Pitch Thin Ball Grid Array (FTBGA)		
XC3S2000			FG(G)320	320-ball Fine-Pitch Ball Grid Array (FBGA)		
XC3S4000			FG(G)456	456-ball Fine-Pitch Ball Grid Array (FBGA)		
XC3S5000			FG(G)676	676-ball Fine-Pitch Ball Grid Array (FBGA)		
			FG(G)900	900-ball Fine-Pitch Ball Grid Array (FBGA)		
			FG(G)1156 ⁽²⁾	1156-ball Fine-Pitch Ball Grid Array (FBGA)		

Notes:

1. The -5 speed grade is exclusively available in the Commercial temperature range.
2. The CP132, CPG132, FG1156, and FGG1156 packages are discontinued. See http://www.xilinx.com/support/documentation/spartan-3_customer_notices.htm.

Revision History

Date	Version	Description
04/11/03	1.0	Initial Xilinx release.
04/24/03	1.1	Updated block RAM, DCM, and multiplier counts for the XC3S50.
12/24/03	1.2	Added the FG320 package.
07/13/04	1.3	Added information on Pb-free packaging options.
01/17/05	1.4	Referenced Spartan-3 XA Automotive FPGA families in Table 1 . Added XC3S50CP132, XC3S2000FG456, XC3S4000FG676 options to Table 3 . Updated Package Marking to show mask revision code, fabrication facility code, and process technology code.
08/19/05	1.5	Added package markings for BGA packages (Figure 3) and CP132/CPG132 packages (Figure 4). Added differential (complementary single-ended) HSTL and SSTL I/O standards.
04/03/06	2.0	Increased number of supported single-ended and differential I/O standards.
04/26/06	2.1	Updated document links.
05/25/07	2.2	Updated Package Marking to allow for dual-marking.
11/30/07	2.3	Added XC3S5000 FG(G)676 to Table 3 . Noted that FG(G)1156 package is being discontinued and updated max I/O count.
06/25/08	2.4	Updated max I/O counts based on FG1156 discontinuation. Clarified dual mark in Package Marking . Updated formatting and links.
12/04/09	2.5	CP132 and CPG132 packages are being discontinued. Added link to Spartan-3 FPGA customer notices. Updated Table 3 with package footprint dimensions.
10/29/12	3.0	Added Notice of Disclaimer section. Per XCN07022 , updated the discontinued FG1156 and FGG1156 package discussion throughout document. Per XCN08011 , updated the discontinued CP132 and CPG132 package discussion throughout document. Although the package is discontinued, updated the marking on Figure 4 . This product is not recommended for new designs.

According to [Figure 7](#), the clock line OTCLK1 connects the CK inputs of the upper registers on the output and three-state paths. Similarly, OTCLK2 connects the CK inputs for the lower registers on the output and three-state paths. The upper and lower registers on the input path have independent clock lines: ICLK1 and ICLK2. The enable line OCE connects the CE inputs of the upper and lower registers on the output path. Similarly, TCE connects the CE inputs for the register pair on the three-state path and ICE does the same for the register pair on the input path. The Set/Reset (SR) line entering the IOB is common to all six registers, as is the Reverse (REV) line.

Each storage element supports numerous options in addition to the control over signal polarity described in the IOB Overview section. These are described in [Table 6](#).

Table 6: Storage Element Options

Option Switch	Function	Specificity
FF/Latch	Chooses between an edge-sensitive flip-flop or a level-sensitive latch	Independent for each storage element.
SYNC/ASYNC	Determines whether SR is synchronous or asynchronous	Independent for each storage element.
SRHIGH/SRLOW	Determines whether SR acts as a Set, which forces the storage element to a logic "1" (SRHIGH) or a Reset, which forces a logic "0" (SRLOW).	Independent for each storage element, except when using FDDR. In the latter case, the selection for the upper element (OFF1 or TFF2) applies to both elements.
INIT1/INIT0	In the event of a Global Set/Reset, after configuration or upon activation of the GSR net, this switch decides whether to set or reset a storage element. By default, choosing SRLOW also selects INIT0; choosing SRHIGH also selects INIT1.	Independent for each storage element, except when using FDDR. In the latter case, selecting INIT0 for one element applies to both elements (even though INIT1 is selected for the other).

Double-Data-Rate Transmission

Double-Data-Rate (DDR) transmission describes the technique of synchronizing signals to both the rising and falling edges of the clock signal. Spartan-3 devices use register-pairs in all three IOB paths to perform DDR operations.

The pair of storage elements on the IOB's Output path (OFF1 and OFF2), used as registers, combine with a special multiplexer to form a DDR D-type flip-flop (FDDR). This primitive permits DDR transmission where output data bits are synchronized to both the rising and falling edges of a clock. It is possible to access this function by placing either an FDDRSE or an FDDRCPE component or symbol into the design. DDR operation requires two clock signals (50% duty cycle), one the inverted form of the other. These signals trigger the two registers in alternating fashion, as shown in [Figure 8](#). Commonly, the Digital Clock Manager (DCM) generates the two clock signals by mirroring an incoming signal, then shifting it 180 degrees. This approach ensures minimal skew between the two signals.

The storage-element-pair on the Three-State path (TFF1 and TFF2) can also be combined with a local multiplexer to form an FDDR primitive. This permits synchronizing the output enable to both the rising and falling edges of a clock. This DDR operation is realized in the same way as for the output path.

The storage-element-pair on the input path (IFF1 and IFF2) allows an I/O to receive a DDR signal. An incoming DDR clock signal triggers one register and the inverted clock signal triggers the other register. In this way, the registers take turns capturing bits of the incoming DDR data signal.

Table 9: Differential I/O Standards

Signal Standard (IOSTANDARD)	V _{CCO} (Volts)		V _{REF} for Inputs (Volts)
	For Outputs	For Inputs	
LDT_25 (ULVDS_25)	2.5	—	—
LVDS_25	2.5	—	—
BLVDS_25	2.5	—	—
LVDSEXT_25	2.5	—	—
LVPECL_25	2.5	—	—
RSDS_25	2.5	—	—
DIFF_HSTL_II_18	1.8	—	—
DIFF_SSTL2_II	2.5	—	—

Notes:

1. See [Table 10](#) for a listing of the differential DCI standards.

The need to supply V_{REF} and V_{CCO} imposes constraints on which standards can be used in the same bank. See [The Organization of IOBs into Banks](#) section for additional guidelines concerning the use of the V_{CCO} and V_{REF} lines.

Digitally Controlled Impedance (DCI)

When the round-trip delay of an output signal—i.e., from output to input and back again—exceeds rise and fall times, it is common practice to add termination resistors to the line carrying the signal. These resistors effectively match the impedance of a device's I/O to the characteristic impedance of the transmission line, thereby preventing reflections that adversely affect signal integrity. However, with the high I/O counts supported by modern devices, adding resistors requires significantly more components and board area. Furthermore, for some packages—e.g., ball grid arrays—it may not always be possible to place resistors close to pins.

DCI answers these concerns by providing two kinds of on-chip terminations: Parallel terminations make use of an integrated resistor network. Series terminations result from controlling the impedance of output drivers. DCI actively adjusts both parallel and series terminations to accurately match the characteristic impedance of the transmission line. This adjustment process compensates for differences in I/O impedance that can result from normal variation in the ambient temperature, the supply voltage and the manufacturing process. When the output driver turns off, the series termination, by definition, approaches a very high impedance; in contrast, parallel termination resistors remain at the targeted values.

DCI is available only for certain I/O standards, as listed in [Table 10](#). DCI is selected by applying the appropriate I/O standard extensions to symbols or components. There are five basic ways to configure terminations, as shown in [Table 11](#). The DCI I/O standard determines which of these terminations is put into effect.

HSTL_I_DCI-, HSTL_III_DCI-, and SSTL2_I_DCI-type outputs do not require the VRN and VRP reference resistors. Likewise, LVDCI-type inputs do not require the VRN and VRP reference resistors. In a bank without any DCI I/O or a bank containing non-DCI I/O and purely HSTL_I_DCI- or HSTL_III_DCI-type outputs, or SSTL2_I_DCI-type outputs or LVDCI-type inputs, the associated VRN and VRP pins can be used as general-purpose I/O pins.

The HSLVDCI (High-Speed LVDCI) standard is intended for bidirectional use. The driver is identical to LVDCI, while the input is identical to HSTL. By using a V_{REF}-referenced input, HSLVDCI allows greater input sensitivity at the receiver than when using a single-ended LVCMOS-type receiver.

Table 10: DCI I/O Standards

Category of Signal Standard	Signal Standard (IOSTANDARD)	V _{CCO} (V)		V _{REF} for Inputs (V)	Termination Type	
		For Outputs	For Inputs		At Output	At Input
Single-Ended						
Gunning Transceiver Logic	GTL_DCI	1.2	1.2	0.8	Single	Single
	GTLP_DCI	1.5	1.5	1.0		
High-Speed Transceiver Logic	HSTL_I_DCI	1.5	1.5	0.75	None	Split
	HSTL_III_DCI	1.5	1.5	0.9	None	Single
	HSTL_I_DCI_18	1.8	1.8	0.9	None	Split
	HSTL_II_DCI_18 DIFF_HSTL_II_18_DCI	1.8	1.8	0.9	Split	
	HSTL_III_DCI_18	1.8	1.8	1.1	None	Single
Low-Voltage CMOS	LVDCI_15	1.5	1.5	—	Controlled impedance driver	None
	LVDCI_18	1.8	1.8	—		
	LVDCI_25	2.5	2.5	—		
	LVDCI_33 ⁽²⁾	3.3	3.3	—		
	LVDCI_DV2_15	1.5	1.5	—	Controlled driver with half-impedance	
	LVDCI_DV2_18	1.8	1.8	—		
	LVDCI_DV2_25	2.5	2.5	—		
	LVDCI_DV2_33	3.3	3.3	—		
Hybrid HSTL Input and LVCMOS Output	HSLVDCI_15	1.5	1.5	0.75	Controlled impedance driver	None
	HSLVDCI_18	1.8	1.8	0.9		
	HSLVDCI_25	2.5	2.5	1.25		
	HSLVDCI_33	3.3	3.3	1.65		
Stub Series Terminated Logic ⁽³⁾	SSTL18_I_DCI	1.8	1.8	0.9	25Ω driver	Split
	SSTL2_I_DCI	2.5	2.5	1.25	25Ω driver	
	SSTL2_II_DCI DIFF_SSTL2_II_DCI	2.5	2.5	1.25	Split with 25Ω driver	
Differential						
Low-Voltage Differential Signaling	LVDS_25_DCI	N/A	2.5	—	None	Split on each line of pair
	LVDS_25_DCI	N/A	2.5	—		

Notes:

- DCI signal standards are not supported in Bank 5 of any Spartan-3 FPGA packaged in a VQ100, CP132, or TQ144 package.
- Equivalent to LVTTTL DCI.
- The SSTL18_II signal standard does not have a DCI equivalent.

upper path), enter the slice and connect directly to the LUT. Once inside the slice, the lower 4-bit path passes through a function generator 'F' (or 'G') that performs logic operations. The function generator's Data output, 'D', offers five possible paths:

- Exit the slice via line 'X' (or 'Y') and return to interconnect.
- Inside the slice, 'X' (or 'Y') serves as an input to the DXMUX (DYMUX) which feeds the data input, 'D', of the FFX (FFY) storage element. The 'Q' output of the storage element drives the line XQ (or YQ) which exits the slice.
- Control the CYMUXF (or CYMUXG) multiplexer on the carry chain.
- With the carry chain, serve as an input to the XORF (or XORG) exclusive-OR gate that performs arithmetic operations, producing a result on 'X' (or 'Y').
- Drive the multiplexer F5MUX to implement logic functions wider than four bits. The 'D' outputs of both the F-LUT and G-LUT serve as data inputs to this multiplexer.

In addition to the main logic paths described above, there are two bypass paths that enter the slice as BX and BY. Once inside the FPGA, BX in the bottom half of the slice (or BY in the top half) can take any of several possible branches:

- Bypass both the LUT and the storage element, then exit the slice as BXOUT (or BYOUT) and return to interconnect.
- Bypass the LUT, then pass through a storage element via the D input before exiting as XQ (or YQ).
- Control the wide function multiplexer F5MUX (or F6MUX).
- Via multiplexers, serve as an input to the carry chain.
- Drives the DI input of the LUT.
- BY can control the REV inputs of both the FFY and FFX storage elements.
- Finally, the DIG_MUX multiplexer can switch BY onto the DIG line, which exits the slice.

Other slice signals shown in [Figure 12](#) are discussed in the sections that follow.

Coarse Phase Shift Outputs of the DLL Component

In addition to CLK0 for zero-phase alignment to the CLKIN signal, the DLL also provides the CLK90, CLK180 and CLK270 outputs for 90°, 180° and 270° phase-shifted signals, respectively. These signals are described in [Table 16, page 33](#). Their relative timing in the Low Frequency Mode is shown in [Figure 22, page 37](#). The CLK90, CLK180 and CLK270 outputs are not available when operating in the High Frequency mode. (See the description of the DLL_FREQUENCY_MODE attribute in [Table 17, page 33](#).) For control in finer increments than 90°, see [Phase Shifter \(PS\), page 39](#).

Basic Frequency Synthesis Outputs of the DLL Component

The DLL component provides basic options for frequency multiplication and division in addition to the more flexible synthesis capability of the DFS component, described in a later section. These operations result in output clock signals with frequencies that are either a fraction (for division) or a multiple (for multiplication) of the incoming clock frequency. The CLK2X output produces an in-phase signal that is twice the frequency of CLKIN. The CLK2X180 output also doubles the frequency, but is 180° out-of-phase with respect to CLKIN. The CLKDIV output generates a clock frequency that is a predetermined fraction of the CLKIN frequency. The CLKDV_DIVIDE attribute determines the factor used to divide the CLKIN frequency. The attribute can be set to various values as described in [Table 17](#). The basic frequency synthesis outputs are described in [Table 16](#). Their relative timing in the Low Frequency Mode is shown in [Figure 22](#).

The CLK2X and CLK2X180 outputs are not available when operating in the High Frequency mode. See the description of the DLL_FREQUENCY_MODE attribute in [Table 18](#).

Duty Cycle Correction of DLL Clock Outputs

The CLK2X⁽¹⁾, CLK2X180, and CLKDV⁽²⁾ output signals ordinarily exhibit a 50% duty cycle—even if the incoming CLKIN signal has a different duty cycle. A 50% duty cycle means that the High and Low times of each clock cycle are equal. The DUTY_CYCLE_CORRECTION attribute determines whether or not duty cycle correction is applied to the CLK0, CLK90, CLK180 and CLK270 outputs. If DUTY_CYCLE_CORRECTION is set to TRUE, then the duty cycle of these four outputs is corrected to 50%. If DUTY_CYCLE_CORRECTION is set to FALSE, then these outputs exhibit the same duty cycle as the CLKIN signal. [Figure 22](#) compares the characteristics of the DLL's output signals to those of the CLKIN signal.

1. The CLK2X output generates a 25% duty cycle clock at the same frequency as the CLKIN signal until the DLL has achieved lock.
 2. The duty cycle of the CLKDV outputs may differ somewhat from 50% (i.e., the signal will be High for less than 50% of the period) when the CLKDV_DIVIDE attribute is set to a non-integer value *and* the DLL is operating in the High Frequency mode.

Table 20: PS Attributes

Attribute	Description	Values
CLKOUT_PHASE_SHIFT	Disables PS component or chooses between Fixed Phase and Variable Phase modes.	NONE, FIXED, VARIABLE
PHASE_SHIFT	Determines size and direction of initial fine phase shift.	Integers from –255 to +255 ⁽¹⁾

Notes:

- The practical range of values will be less when $T_{CLKIN} > FINE_SHIFT_RANGE$ in the Fixed Phase mode, also when $T_{CLKIN} > (FINE_SHIFT_RANGE)/2$ in the Variable Phase mode. the $FINE_SHIFT_RANGE$ represents the sum total delay of all taps.

The Variable Phase Mode

The “Variable Phase” mode dynamically adjusts the fine phase shift over time using three inputs to the PS component, namely PSEN, PSCLK and PSINCDEC, as defined in [Table 21](#).

After device configuration, the PS component initially determines T_{PS} by evaluating Equation (4) for the value assigned to the PHASE_SHIFT attribute. Then to dynamically adjust that phase shift, use the three PS inputs to increase or decrease the fine phase shift.

PSINCDEC is synchronized to the PSCLK clock signal, which is enabled by asserting PSEN. It is possible to drive the PSCLK input with the CLKIN signal or any other clock signal. A request for phase adjustment is entered as follows: For each PSCLK cycle that PSINCDEC is High, the PS component adds 1/256 of a CLKIN cycle to T_{PS} . Similarly, for each enabled PSCLK cycle that PSINCDEC is Low, the PS component subtracts 1/256 of a CLKIN cycle from T_{PS} . The phase adjustment may require as many as 100 CLKIN cycles plus three PSCLK cycles to take effect, at which point the output PSDONE goes High for one PSCLK cycle. This pulse indicates that the PS component has finished the present adjustment and is now ready for the next request. Asserting the Reset (RST) input, returns T_{PS} to its original shift time, as determined by the PHASE_SHIFT attribute value. The set of waveforms in section [c] of [Figure 23, page 41](#) illustrates the relationship between CLKFB and CLKIN in the Variable Phase mode.

Table 21: Signals for Variable Phase Mode

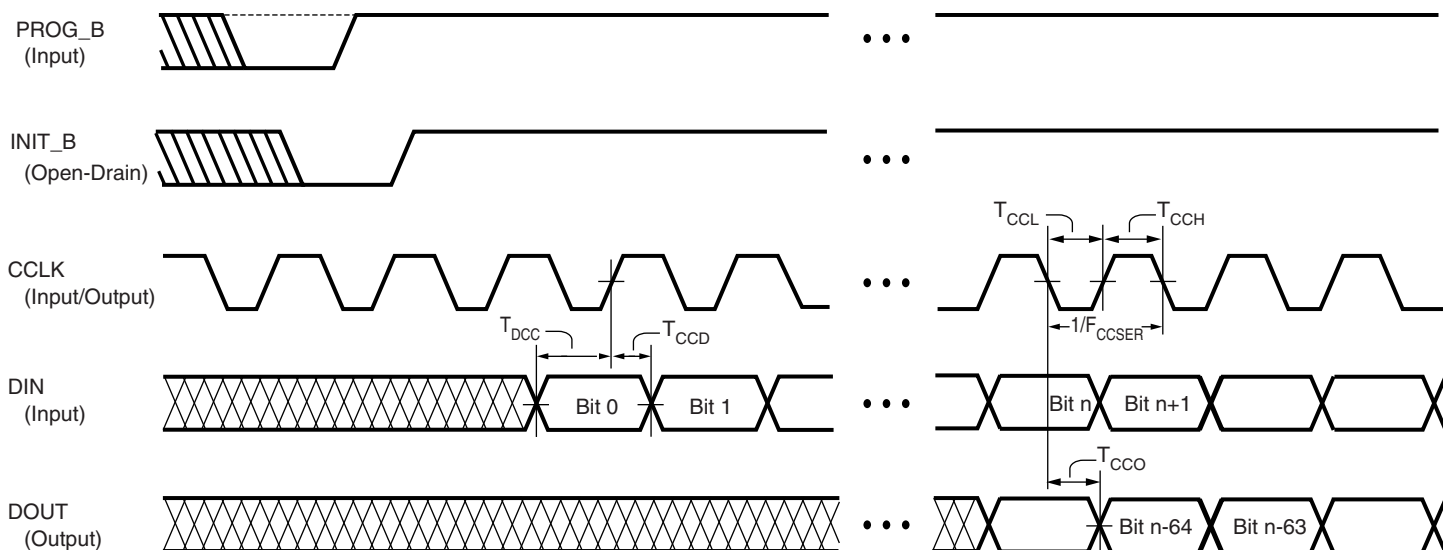
Signal	Direction	Description
PSEN ⁽¹⁾	Input	Enables PSCLK for variable phase adjustment.
PSCLK ⁽¹⁾	Input	Clock to synchronize phase shift adjustment.
PSINCDEC ⁽¹⁾	Input	Chooses between increment and decrement for phase adjustment. It is synchronized to the PSCLK signal.
PSDONE	Output	Goes High to indicate that present phase adjustment is complete and PS component is ready for next phase adjustment request. It is synchronized to the PSCLK signal.

Notes:

- It is possible to program this input for either a true or inverted polarity

Revision History

Date	Version No.	Description
04/11/03	1.0	Initial Xilinx release
05/19/03	1.1	Added Block RAM column, DCMs, and multipliers to XC3S50 descriptions.
07/11/03	1.2	Explained the configuration port <i>Persist</i> option in Slave Parallel Mode (SelectMAP) section. Updated Figure 8 and Double-Data-Rate Transmission section to indicate that DDR clocking for the XC3S50 is the same as that for all other Spartan-3 devices. Updated description of I/O voltage tolerance in ESD Protection section. In Table 10 , changed input termination type for DCI version of the LVCMOS standard to <i>None</i> . Added additional flexibility for making DLL connections in Figure 21 and accompanying text. In the Configuration section, inserted an explanation of how to choose power supplies for the configuration interface, including guidelines for achieving 3.3V-tolerance.
08/24/04	1.3	Showed inversion of 3-state signal (Figure 7). Clarified description of pull-up and pull-down resistors (Table 6 and page 13). Added information on operating block RAM with multipliers to page 26 . Corrected output buffer name in Figure 21 . Corrected description of how DOUT is synchronized to CCLK (page 47).
08/19/05	1.4	Corrected description of WRITE_FIRST and READ_FIRST in Table 13 . Added note regarding address setup and hold time requirements whenever a block RAM port is enabled (Table 13). Added information in the maximum length of a Configuration daisy-chain. Added reference to XAPP453 in 3.3V-Tolerant Configuration Interface section. Added information on the STATUS[2] DCM output (Table 23). Added information on CCLK behavior and termination recommendations to Configuration . Added Additional Configuration Details section. Added Powering Spartan-3 FPGAs section. Removed GSR from Figure 31 because its timing is not programmable.
04/03/06	2.0	Updated Figure 7 . Updated Figure 14 . Updated Table 10 . Updated Figure 22 . Corrected Platform Flash supply voltage name and value in Figure 26 and Figure 28 . Added No Internal Charge Pumps or Free-Running Oscillators . Corrected a few minor typographical errors.
04/26/06	2.1	Added more information on the pull-up resistors that are active during configuration to Configuration . Added information to Boundary-Scan (JTAG) Mode about potential interactions when configuring via JTAG if the mode select pins are set for other than JTAG.
05/25/07	2.2	Added Spartan-3 FPGA Design Documentation . Noted SSTL2_I_DCI 25-Ohm driver in Table 10 and Table 11 . Added note that pull-down is active during boundary scan tests.
11/30/07	2.3	Updated links to documentation on xilinx.com.
06/25/08	2.4	Added HSLVDCI to Table 10 . Updated formatting and links.
12/04/09	2.5	Updated HSLVDCI description in Digitally Controlled Impedance (DCI) . Updated the low-voltage differential signaling V _{CCO} values in Table 10 . Noted that the CP132 package is being discontinued in The Organization of IOBs into Banks . Updated rule 4 in Rules Concerning Banks . Added software version requirement in The Fixed Phase Mode .
10/29/12	3.0	Added Notice of Disclaimer . Per XCN07022 , updated the discontinued FG1156 and FGG1156 package discussion throughout document. Per XCN08011 , updated the discontinued CP132 and CPG132 package discussion throughout document. This product is not recommended for new designs.



DS099-3_04_071604

Figure 37: Waveforms for Master and Slave Serial Configuration

Table 66: Timing for the Master and Slave Serial Configuration Modes

Symbol	Description	Slave/ Master	All Speed Grades		Units	
			Min	Max		
Clock-to-Output Times						
T _{CCO}	The time from the falling transition on the CCLK pin to data appearing at the DOUT pin	Both	1.5	12.0	ns	
Setup Times						
T _{DCC}	The time from the setup of data at the DIN pin to the rising transition at the CCLK pin	Both	10.0	—	ns	
Hold Times						
T _{CCD}	The time from the rising transition at the CCLK pin to the point when data is last held at the DIN pin	Both	0	—	ns	
Clock Timing						
T _{CCH}	CCLK input pin High pulse width		Slave	5.0	∞	ns
T _{CCL}	CCLK input pin Low pulse width			5.0	∞	ns
F _{CCSER}	Frequency of the clock signal at the CCLK input pin	No bitstream compression		0	66 ⁽²⁾	MHz
		With bitstream compression		0	20	MHz
		During STARTUP phase		0	50	MHz
ΔF _{CCSER}	Variation from the CCLK output frequency set using the ConfigRate BitGen option		Master	–50%	+50%	—

Notes:

1. The numbers in this table are based on the operating conditions set forth in Table 32.
2. For serial configuration with a daisy-chain of multiple FPGAs, the maximum limit is 25 MHz.

All VCCAUX inputs must be connected together and to the +2.5V voltage supply. Furthermore, there must be sufficient supply decoupling to guarantee problem-free operation, as described in [XAPP623](#).

Because VCCAUX connects to the DCMs and the DCMs are sensitive to voltage changes, be sure that the VCCAUX supply and the ground return paths are designed for low noise and low voltage drop, especially that caused by a large number of simultaneous switching I/Os.

GND Type: Ground

All GND pins must be connected and have a low resistance path back to the various VCCO, VCCINT, and VCCAUX supplies.

Pin Behavior During Configuration

[Table 79](#) shows how various pins behave during the FPGA configuration process. The actual behavior depends on the values applied to the M2, M1, and M0 mode select pins and the HSWAP_EN pin. The mode select pins determine which of the DUAL type pins are active during configuration. In JTAG configuration mode, none of the DUAL-type pins are used for configuration and all behave as user-I/O pins.

All DUAL-type pins not actively used during configuration and all I/O-type, DCI-type, VREF-type, GCLK-type pins are high impedance (floating, three-stated, Hi-Z) during the configuration process. These pins are indicated in [Table 79](#) as shaded table entries or cells. These pins have a pull-up resistor to their associated VCCO if the HSWAP_EN pin is Low. When HSWAP_EN is High, these pull-up resistors are disabled during configuration.

Some pins always have an active pull-up resistor during configuration, regardless of the value applied to the HSWAP_EN pin. After configuration, these pull-up resistors are controlled by [Bitstream Options](#).

- All the dedicated CONFIG-type configuration pins (CCLK, PROG_B, DONE, M2, M1, M0, and HSWAP_EN) have a pull-up resistor to VCCAUX.
- All JTAG-type pins (TCK, TDI, TMS, TDO) have a pull-up resistor to VCCAUX.
- The INIT_B DUAL-purpose pin has a pull-up resistor to VCCO_4 or VCCO_BOTTOM, depending on package style.

After configuration completes, some pins have optional behavior controlled by the configuration bitstream loaded into the part. For example, via the bitstream, all unused I/O pins can be collectively configured as input pins with either a pull-up resistor, a pull-down resistor, or be left in a high-impedance state.

Table 79: Pin Behavior After Power-Up, During Configuration

Pin Name	Configuration Mode Settings <M2:M1:M0>					Bitstream Configuration Option
	Serial Modes		SelectMap Parallel Modes		JTAG Mode <1:0:1>	
	Master <0:0:0>	Slave <1:1:1>	Master <0:1:1>	Slave <1:1:0>		
I/O: General-purpose I/O pins						
IO						UnusedPin
IO_Lxxy_#						UnusedPin
DUAL: Dual-purpose configuration pins						
IO_Lxxy_#/DIN/D0	DIN (I)	DIN (I)	D0 (I/O)	D0 (I/O)		Persist UnusedPin
IO_Lxxy_#/D1			D1 (I/O)	D1 (I/O)		Persist UnusedPin
IO_Lxxy_#/D2			D2 (I/O)	D2 (I/O)		Persist UnusedPin
IO_Lxxy_#/D3			D3 (I/O)	D3 (I/O)		Persist UnusedPin
IO_Lxxy_#/D4			D4 (I/O)	D4 (I/O)		Persist UnusedPin

Table 91: TQ144 Package Pinout (Cont'd)

Bank	XC3S50, XC3S200, XC3S400 Pin Name	TQ144 Pin Number	Type
2	IO_L23N_2/VREF_2	P98	VREF
2	IO_L23P_2	P97	I/O
2	IO_L24N_2	P96	I/O
2	IO_L24P_2	P95	I/O
2	IO_L40N_2	P93	I/O
2	IO_L40P_2/VREF_2	P92	VREF
3	IO	P76	I/O
3	IO_L01N_3/VRP_3	P74	DCI
3	IO_L01P_3/VRN_3	P73	DCI
3	IO_L20N_3	P78	I/O
3	IO_L20P_3	P77	I/O
3	IO_L21N_3	P80	I/O
3	IO_L21P_3	P79	I/O
3	IO_L22N_3	P83	I/O
3	IO_L22P_3	P82	I/O
3	IO_L23N_3	P85	I/O
3	IO_L23P_3/VREF_3	P84	VREF
3	IO_L24N_3	P87	I/O
3	IO_L24P_3	P86	I/O
3	IO_L40N_3/VREF_3	P90	VREF
3	IO_L40P_3	P89	I/O
4	IO/VREF_4	P70	VREF
4	IO_L01N_4/VRP_4	P69	DCI
4	IO_L01P_4/VRN_4	P68	DCI
4	IO_L27N_4/DIN/D0	P65	DUAL
4	IO_L27P_4/D1	P63	DUAL
4	IO_L30N_4/D2	P60	DUAL
4	IO_L30P_4/D3	P59	DUAL
4	IO_L31N_4/INIT_B	P58	DUAL
4	IO_L31P_4/DOOUT/BUSY	P57	DUAL
4	IO_L32N_4/GCLK1	P56	GCLK
4	IO_L32P_4/GCLK0	P55	GCLK
5	IO/VREF_5	P44	VREF
5	IO_L01N_5/RDWR_B	P41	DUAL
5	IO_L01P_5/CS_B	P40	DUAL
5	IO_L28N_5/D6	P47	DUAL
5	IO_L28P_5/D7	P46	DUAL
5	IO_L31N_5/D4	P51	DUAL
5	IO_L31P_5/D5	P50	DUAL
5	IO_L32N_5/GCLK3	P53	GCLK

Table 103: FG676 Package Pinout (Cont'd)

Bank	XC3S1000 Pin Name	XC3S1500 Pin Name	XC3S2000 Pin Name	XC3S4000 Pin Name	XC3S5000 Pin Name	FG676 Pin Number	Type
N/A	GND	GND	GND	GND	GND	R16	GND
N/A	GND	GND	GND	GND	GND	R17	GND
N/A	GND	GND	GND	GND	GND	R23	GND
N/A	GND	GND	GND	GND	GND	T10	GND
N/A	GND	GND	GND	GND	GND	T11	GND
N/A	GND	GND	GND	GND	GND	T12	GND
N/A	GND	GND	GND	GND	GND	T13	GND
N/A	GND	GND	GND	GND	GND	T14	GND
N/A	GND	GND	GND	GND	GND	T15	GND
N/A	GND	GND	GND	GND	GND	T16	GND
N/A	GND	GND	GND	GND	GND	T17	GND
N/A	GND	GND	GND	GND	GND	U11	GND
N/A	GND	GND	GND	GND	GND	U12	GND
N/A	GND	GND	GND	GND	GND	U15	GND
N/A	GND	GND	GND	GND	GND	U16	GND
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	A2	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	A9	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	A18	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	A25	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AE1	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AE26	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AF2	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AF9	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AF18	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AF25	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	B1	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	B26	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	J1	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	J26	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	V1	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	V26	VCCAUX
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	H8	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	H19	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	J9	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	J10	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	J17	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	J18	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	K9	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	K10	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	K17	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	K18	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	U9	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	U10	VCCINT

Table 107: FG900 Package Pinout (Cont'd)

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
2	IO_L04N_2	IO_L04N_2	E29	I/O
2	IO_L04P_2	IO_L04P_2	E30	I/O
2	IO_L05N_2	IO_L05N_2	F28	I/O
2	IO_L05P_2	IO_L05P_2	F29	I/O
2	IO_L06N_2	IO_L06N_2	G27	I/O
2	IO_L06P_2	IO_L06P_2	G28	I/O
2	IO_L07N_2	IO_L07N_2	G29	I/O
2	IO_L07P_2	IO_L07P_2	G30	I/O
2	IO_L08N_2	IO_L08N_2	G25	I/O
2	IO_L08P_2	IO_L08P_2	H24	I/O
2	IO_L09N_2/VREF_2	IO_L09N_2/VREF_2	H25	VREF
2	IO_L09P_2	IO_L09P_2	H26	I/O
2	IO_L10N_2	IO_L10N_2	H27	I/O
2	IO_L10P_2	IO_L10P_2	H28	I/O
2	IO_L12N_2	IO_L12N_2	H29	I/O
2	IO_L12P_2	IO_L12P_2	H30	I/O
2	IO_L13N_2	IO_L13N_2	J26	I/O
2	IO_L13P_2/VREF_2	IO_L13P_2/VREF_2	J27	VREF
2	IO_L14N_2	IO_L14N_2	J29	I/O
2	IO_L14P_2	IO_L14P_2	J30	I/O
2	IO_L15N_2	IO_L15N_2	J23	I/O
2	IO_L15P_2	IO_L15P_2	K22	I/O
2	IO_L16N_2	IO_L16N_2	K24	I/O
2	IO_L16P_2	IO_L16P_2	K25	I/O
2	IO_L19N_2	IO_L19N_2	L25	I/O
2	IO_L19P_2	IO_L19P_2	L26	I/O
2	IO_L20N_2	IO_L20N_2	L27	I/O
2	IO_L20P_2	IO_L20P_2	L28	I/O
2	IO_L21N_2	IO_L21N_2	L29	I/O
2	IO_L21P_2	IO_L21P_2	L30	I/O
2	IO_L22N_2	IO_L22N_2	M22	I/O
2	IO_L22P_2	IO_L22P_2	M23	I/O
2	IO_L23N_2/VREF_2	IO_L23N_2/VREF_2	M24	VREF
2	IO_L23P_2	IO_L23P_2	M25	I/O
2	IO_L24N_2	IO_L24N_2	M27	I/O
2	IO_L24P_2	IO_L24P_2	M28	I/O
2	IO_L26N_2	IO_L26N_2	M21	I/O
2	IO_L26P_2	IO_L26P_2	N21	I/O
2	IO_L27N_2	IO_L27N_2	N22	I/O
2	IO_L27P_2	IO_L27P_2	N23	I/O

Table 107: FG900 Package Pinout (Cont'd)

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
2	VCCO_2	VCCO_2	J28	VCCO
2	VCCO_2	VCCO_2	N28	VCCO
3	IO	IO	AB25	I/O
3	IO_L01N_3/VRP_3	IO_L01N_3/VRP_3	AH30	DCI
3	IO_L01P_3/VRN_3	IO_L01P_3/VRN_3	AH29	DCI
3	IO_L02N_3/VREF_3	IO_L02N_3/VREF_3	AG28	VREF
3	IO_L02P_3	IO_L02P_3	AG27	I/O
3	IO_L03N_3	IO_L03N_3	AG30	I/O
3	IO_L03P_3	IO_L03P_3	AG29	I/O
3	IO_L04N_3	IO_L04N_3	AF30	I/O
3	IO_L04P_3	IO_L04P_3	AF29	I/O
3	IO_L05N_3	IO_L05N_3	AE26	I/O
3	IO_L05P_3	IO_L05P_3	AF27	I/O
3	IO_L06N_3	IO_L06N_3	AE29	I/O
3	IO_L06P_3	IO_L06P_3	AE28	I/O
3	IO_L07N_3	IO_L07N_3	AD28	I/O
3	IO_L07P_3	IO_L07P_3	AD27	I/O
3	IO_L08N_3	IO_L08N_3	AD30	I/O
3	IO_L08P_3	IO_L08P_3	AD29	I/O
3	IO_L09N_3	IO_L09N_3	AC24	I/O
3	IO_L09P_3/VREF_3	IO_L09P_3/VREF_3	AD25	VREF
3	IO_L10N_3	IO_L10N_3	AC26	I/O
3	IO_L10P_3	IO_L10P_3	AC25	I/O
3	IO_L11N_3	IO_L11N_3	AC28	I/O
3	IO_L11P_3	IO_L11P_3	AC27	I/O
3	IO_L13N_3/VREF_3	IO_L13N_3/VREF_3	AC30	VREF
3	IO_L13P_3	IO_L13P_3	AC29	I/O
3	IO_L14N_3	IO_L14N_3	AB27	I/O
3	IO_L14P_3	IO_L14P_3	AB26	I/O
3	IO_L15N_3	IO_L15N_3	AB30	I/O
3	IO_L15P_3	IO_L15P_3	AB29	I/O
3	IO_L16N_3	IO_L16N_3	AA22	I/O
3	IO_L16P_3	IO_L16P_3	AB23	I/O
3	IO_L17N_3	IO_L17N_3	AA25	I/O
3	IO_L17P_3/VREF_3	IO_L17P_3/VREF_3	AA24	VREF
3	IO_L19N_3	IO_L19N_3	AA29	I/O
3	IO_L19P_3	IO_L19P_3	AA28	I/O
3	IO_L20N_3	IO_L20N_3	Y21	I/O
3	IO_L20P_3	IO_L20P_3	AA21	I/O
3	IO_L21N_3	IO_L21N_3	Y24	I/O

Table 107: FG900 Package Pinout (Cont'd)

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
N/A	GND	GND	K30	GND
N/A	GND	GND	P30	GND
N/A	GND	GND	U30	GND
N/A	GND	GND	AA30	GND
N/A	GND	GND	AE30	GND
N/A	GND	GND	AJ30	GND
N/A	GND	GND	AK30	GND
N/A	GND	GND	AK2	GND
N/A	VCCAUX	VCCAUX	F4	VCCAUX
N/A	VCCAUX	VCCAUX	K4	VCCAUX
N/A	VCCAUX	VCCAUX	P4	VCCAUX
N/A	VCCAUX	VCCAUX	U4	VCCAUX
N/A	VCCAUX	VCCAUX	AA4	VCCAUX
N/A	VCCAUX	VCCAUX	AE4	VCCAUX
N/A	VCCAUX	VCCAUX	D6	VCCAUX
N/A	VCCAUX	VCCAUX	AG6	VCCAUX
N/A	VCCAUX	VCCAUX	D10	VCCAUX
N/A	VCCAUX	VCCAUX	AG10	VCCAUX
N/A	VCCAUX	VCCAUX	D14	VCCAUX
N/A	VCCAUX	VCCAUX	AG14	VCCAUX
N/A	VCCAUX	VCCAUX	D17	VCCAUX
N/A	VCCAUX	VCCAUX	AG17	VCCAUX
N/A	VCCAUX	VCCAUX	D21	VCCAUX
N/A	VCCAUX	VCCAUX	AG21	VCCAUX
N/A	VCCAUX	VCCAUX	D25	VCCAUX
N/A	VCCAUX	VCCAUX	AG25	VCCAUX
N/A	VCCAUX	VCCAUX	F27	VCCAUX
N/A	VCCAUX	VCCAUX	K27	VCCAUX
N/A	VCCAUX	VCCAUX	P27	VCCAUX
N/A	VCCAUX	VCCAUX	U27	VCCAUX
N/A	VCCAUX	VCCAUX	AA27	VCCAUX
N/A	VCCAUX	VCCAUX	AE27	VCCAUX
N/A	VCCINT	VCCINT	L11	VCCINT
N/A	VCCINT	VCCINT	R11	VCCINT
N/A	VCCINT	VCCINT	T11	VCCINT
N/A	VCCINT	VCCINT	Y11	VCCINT
N/A	VCCINT	VCCINT	M12	VCCINT
N/A	VCCINT	VCCINT	N12	VCCINT
N/A	VCCINT	VCCINT	P12	VCCINT
N/A	VCCINT	VCCINT	U12	VCCINT

Table 107: FG900 Package Pinout (Cont'd)

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
N/A	VCCINT	VCCINT	V12	VCCINT
N/A	VCCINT	VCCINT	W12	VCCINT
N/A	VCCINT	VCCINT	M13	VCCINT
N/A	VCCINT	VCCINT	W13	VCCINT
N/A	VCCINT	VCCINT	M14	VCCINT
N/A	VCCINT	VCCINT	W14	VCCINT
N/A	VCCINT	VCCINT	L15	VCCINT
N/A	VCCINT	VCCINT	Y15	VCCINT
N/A	VCCINT	VCCINT	L16	VCCINT
N/A	VCCINT	VCCINT	Y16	VCCINT
N/A	VCCINT	VCCINT	M17	VCCINT
N/A	VCCINT	VCCINT	W17	VCCINT
N/A	VCCINT	VCCINT	M18	VCCINT
N/A	VCCINT	VCCINT	W18	VCCINT
N/A	VCCINT	VCCINT	M19	VCCINT
N/A	VCCINT	VCCINT	N19	VCCINT
N/A	VCCINT	VCCINT	P19	VCCINT
N/A	VCCINT	VCCINT	U19	VCCINT
N/A	VCCINT	VCCINT	V19	VCCINT
N/A	VCCINT	VCCINT	W19	VCCINT
N/A	VCCINT	VCCINT	L20	VCCINT
N/A	VCCINT	VCCINT	R20	VCCINT
N/A	VCCINT	VCCINT	T20	VCCINT
N/A	VCCINT	VCCINT	Y20	VCCINT
VCCAUX	CCLK	CCLK	AH28	CONFIG
VCCAUX	DONE	DONE	AJ28	CONFIG
VCCAUX	HSWAP_EN	HSWAP_EN	A3	CONFIG
VCCAUX	M0	M0	AJ3	CONFIG
VCCAUX	M1	M1	AH3	CONFIG
VCCAUX	M2	M2	AK3	CONFIG
VCCAUX	PROG_B	PROG_B	B3	CONFIG
VCCAUX	TCK	TCK	B28	JTAG
VCCAUX	TDI	TDI	C3	JTAG
VCCAUX	TDO	TDO	C28	JTAG
VCCAUX	TMS	TMS	A28	JTAG

Table 110: FG1156 Package Pinout (Cont'd)

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
0	IO_L23P_0	IO_L23P_0	J15	I/O
0	IO_L24N_0	IO_L24N_0	G15	I/O
0	IO_L24P_0	IO_L24P_0	F15	I/O
0	IO_L25N_0	IO_L25N_0	D15	I/O
0	IO_L25P_0	IO_L25P_0	C15	I/O
0	IO_L26N_0	IO_L26N_0	B15	I/O
0	IO_L26P_0/VREF_0	IO_L26P_0/VREF_0	A15	VREF
0	IO_L27N_0	IO_L27N_0	G16	I/O
0	IO_L27P_0	IO_L27P_0	F16	I/O
0	IO_L28N_0	IO_L28N_0	C16	I/O
0	IO_L28P_0	IO_L28P_0	B16	I/O
0	IO_L29N_0	IO_L29N_0	J17	I/O
0	IO_L29P_0	IO_L29P_0	H17	I/O
0	IO_L30N_0	IO_L30N_0	G17	I/O
0	IO_L30P_0	IO_L30P_0	F17	I/O
0	IO_L31N_0	IO_L31N_0	D17	I/O
0	IO_L31P_0/VREF_0	IO_L31P_0/VREF_0	C17	VREF
0	IO_L32N_0/GCLK7	IO_L32N_0/GCLK7	B17	GCLK
0	IO_L32P_0/GCLK6	IO_L32P_0/GCLK6	A17	GCLK
0	N.C. (◆)	IO_L33N_0	D7	I/O
0	N.C. (◆)	IO_L33P_0	C7	I/O
0	N.C. (◆)	IO_L34N_0	B7	I/O
0	N.C. (◆)	IO_L34P_0	A7	I/O
0	IO_L35N_0	IO_L35N_0	E8	I/O
0	IO_L35P_0	IO_L35P_0	D8	I/O
0	IO_L36N_0	IO_L36N_0	B8	I/O
0	IO_L36P_0	IO_L36P_0	A8	I/O
0	IO_L37N_0	IO_L37N_0	D10	I/O
0	IO_L37P_0	IO_L37P_0	C10	I/O
0	IO_L38N_0	IO_L38N_0	B10	I/O
0	IO_L38P_0	IO_L38P_0	A10	I/O
0	N.C. (◆)	IO_L39N_0	G11	I/O
0	N.C. (◆)	IO_L39P_0	F11	I/O
0	N.C. (◆)	IO_L40N_0	B11	I/O
0	N.C. (◆)	IO_L40P_0	A11	I/O
0	VCCO_0	VCCO_0	B13	VCCO
0	VCCO_0	VCCO_0	C4	VCCO
0	VCCO_0	VCCO_0	C8	VCCO
0	VCCO_0	VCCO_0	D11	VCCO
0	VCCO_0	VCCO_0	D16	VCCO

Table 110: FG1156 Package Pinout (Cont'd)

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
5	IO_L04P_5	IO_L04P_5	AL6	I/O
5	IO_L05N_5	IO_L05N_5	AP6	I/O
5	IO_L05P_5	IO_L05P_5	AN6	I/O
5	IO_L06N_5	IO_L06N_5	AK7	I/O
5	IO_L06P_5	IO_L06P_5	AJ7	I/O
5	IO_L07N_5	IO_L07N_5	AG10	I/O
5	IO_L07P_5	IO_L07P_5	AF10	I/O
5	IO_L08N_5	IO_L08N_5	AJ10	I/O
5	IO_L08P_5	IO_L08P_5	AH10	I/O
5	IO_L09N_5	IO_L09N_5	AM10	I/O
5	IO_L09P_5	IO_L09P_5	AL10	I/O
5	IO_L10N_5/VRP_5	IO_L10N_5/VRP_5	AP10	DCI
5	IO_L10P_5/VRN_5	IO_L10P_5/VRN_5	AN10	DCI
5	IO_L11N_5/VREF_5	IO_L11N_5/VREF_5	AP11	VREF
5	IO_L11P_5	IO_L11P_5	AN11	I/O
5	IO_L12N_5	IO_L12N_5	AF12	I/O
5	IO_L12P_5	IO_L12P_5	AE12	I/O
5	IO_L13N_5	IO_L13N_5	AJ12	I/O
5	IO_L13P_5	IO_L13P_5	AH12	I/O
5	IO_L14N_5	IO_L14N_5	AL12	I/O
5	IO_L14P_5	IO_L14P_5	AK12	I/O
5	IO_L15N_5	IO_L15N_5	AP12	I/O
5	IO_L15P_5	IO_L15P_5	AN12	I/O
5	IO_L16N_5	IO_L16N_5	AE13	I/O
5	IO_L16P_5	IO_L16P_5	AD13	I/O
5	IO_L17N_5	IO_L17N_5	AH13	I/O
5	IO_L17P_5	IO_L17P_5	AG13	I/O
5	IO_L18N_5	IO_L18N_5	AM13	I/O
5	IO_L18P_5	IO_L18P_5	AL13	I/O
5	IO_L19N_5	IO_L19N_5	AG14	I/O
5	IO_L19P_5/VREF_5	IO_L19P_5/VREF_5	AF14	VREF
5	IO_L20N_5	IO_L20N_5	AJ14	I/O
5	IO_L20P_5	IO_L20P_5	AH14	I/O
5	IO_L21N_5	IO_L21N_5	AM14	I/O
5	IO_L21P_5	IO_L21P_5	AL14	I/O
5	IO_L22N_5	IO_L22N_5	AP14	I/O
5	IO_L22P_5	IO_L22P_5	AN14	I/O
5	IO_L23N_5	IO_L23N_5	AF15	I/O
5	IO_L23P_5	IO_L23P_5	AE15	I/O
5	IO_L24N_5	IO_L24N_5	AJ15	I/O

FG1156 Footprint

Top Left Corner of FG1156 Package (Top View)

XC3S4000
(712 max. user I/O)

621 I/O: Unrestricted, general-purpose user I/O

55 VREF: User I/O or input voltage reference for bank

73 N.C.: Unconnected pins for XC3S4000 (◆)

XC3S5000
(784 max. user I/O)

692 I/O: Unrestricted, general-purpose user I/O

56 VREF: User I/O or input voltage reference for bank

1 N.C.: Unconnected pins for XC3S5000 (■)

		Bank 0																
		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17
Bank 7	A	GND	GND	I/O L01P_0 VRN_0	I/O L02P_0	GND	I/O L05P_0 VREF_0	I/O L34P_0 ◆	I/O L36P_0	GND	I/O L38P_0	I/O L40P_0 ◆	I/O L15P_0	GND	I/O L22P_0	I/O L26P_0 VREF_0	GND	I/O L32P_0 GCLK6
	B	GND	GND	I/O L01N_0 VRP_0	I/O L02N_0	I/O L03P_0	I/O L05N_0	I/O L34N_0 ◆	I/O L36N_0	I/O	I/O L38N_0	I/O L40N_0 ◆	I/O L15N_0	VCCO_0	I/O L22N_0	I/O L26N_0	I/O L28P_0	I/O L32N_0 GCLK7
	C	I/O L01N_7 VRP_7	I/O L01P_7 VRN_7	GND	VCCO_0	I/O L03N_0	I/O L04P_0	I/O L33P_0 ◆	VCCO_0	I/O L08P_0	I/O L37P_0	GND	I/O L14P_0	I/O L17P_0	I/O L21P_0	I/O L25P_0	I/O L28N_0	I/O L31P_0 VREF_0
	D	I/O L02N_7	I/O L02P_7	VCCO_7	PROG_B	IO VREF_0	I/O L04N_0	I/O L33N_0 ◆	I/O L35P_0	I/O L08N_0	I/O L37N_0	VCCO_0	I/O L14N_0	I/O L17N_0	I/O L21N_0	I/O L25N_0	VCCO_0	I/O L31N_0
	E	GND	I/O L03N_7 VREF_7	I/O L03P_7	TDI	GND	VCCAUX	I/O L06P_0	I/O L35N_0	GND	IO VREF_0	VCCAUX	I/O L13P_0	GND	I/O L20P_0	VCCAUX	GND	I/O
	F	I/O L05N_7	I/O L05P_7	I/O L04N_7	I/O L04P_7	VCCAUX	I/O	I/O L06N_0	I/O	I/O L07P_0	I/O L10P_0	I/O L39P_0 ◆	I/O L13N_0	VCCO_0	I/O L20N_0	I/O L24P_0	I/O L27P_0	I/O L30P_0
	G	I/O	I/O	I/O L41N_7 ◆	I/O L41P_7 ◆	I/O L06N_7	I/O L06P_7	GND	VCCO_0	I/O L07N_0	I/O L10N_0	I/O L39N_0 ◆	I/O	I/O L16P_0	I/O L19P_0	I/O L24N_0	I/O L27N_0	I/O L30N_0
	H	I/O L08N_7	I/O L08P_7	VCCO_7	I/O L10P_7 VREF_7	I/O L07N_7	I/O L07P_7	VCCO_7	I/O	I/O	I/O L09P_0	VCCO_0	I/O L12P_0	I/O L16N_0	I/O L19N_0	VCCO_0	VCCAUX	I/O L29P_0
	J	GND	I/O L11N_7	I/O L11P_7	I/O L10N_7	GND	I/O L09N_7	I/O L09P_7	I/O L12P_7	I/O ◆	I/O L09N_0	I/O	I/O L12N_0	GND	IO VREF_0	I/O L23P_0	GND	I/O L29N_0
	K	I/O L16N_7	I/O L16P_7 VREF_7	I/O L15N_7	I/O L15P_7	I/O L14N_7	I/O L14P_7	I/O L13N_7	I/O L13P_7	I/O L12N_7	GND	I/O ◆	I/O L11P_0	I/O	I/O L18P_0	I/O L23N_0	I/O	I/O
	L	I/O L19N_7 VREF_7	I/O L19P_7	GND	VCCO_7	VCCAUX	I/O L44N_7 ◆	I/O L44P_7 ◆	VCCO_7	I/O L17N_7	I/O L17P_7	HSWAP_EN	I/O L11N_0	I/O	I/O L18N_0	IO VREF_0	I/O	I/O
	M	I/O L45N_7	I/O L45P_7	I/O L23N_7	I/O L23P_7	I/O L22N_7	I/O L22P_7	I/O L21N_7	I/O L21P_7	I/O L24P_7	I/O L20N_7	I/O L20P_7	VCCINT	VCCO_0	VCCO_0	VCCO_0	VCCO_0	VCCINT
	N	GND	VCCO_7	I/O L25N_7	I/O L25P_7	GND	VCCO_7	I/O L46N_7	I/O L46P_7	GND	I/O L24N_7	I/O L26P_7	VCCO_7	VCCINT	VCCINT	VCCINT	VCCINT	GND
	P	I/O L49N_7	I/O L49P_7	I/O L29N_7	I/O L29P_7	I/O L28N_7	I/O L28P_7	I/O L27N_7	I/O L27P_7 VREF_7	I/O L47N_7 ◆	I/O L47P_7 ◆	I/O L26N_7	VCCO_7	VCCINT	GND	GND	GND	GND
	R	I/O L32N_7	I/O L32P_7	I/O L31N_7	I/O L31P_7	VCCAUX	I/O L30N_7	I/O L30P_7	VCCO_7	I/O L33P_7	I/O L50N_7	I/O L50P_7	VCCO_7	VCCINT	GND	GND	GND	GND
	T	GND	I/O L35N_7	I/O L35P_7	VCCO_7	GND	I/O L34N_7	I/O L34P_7	VCCAUX	GND	I/O L33N_7	I/O L51P_7 ◆	VCCO_7	VCCINT	GND	GND	GND	GND
	U	I/O L40N_7 VREF_7	I/O L40P_7	I/O L39N_7	I/O L39P_7	I/O L38N_7	I/O L38P_7	I/O L37N_7	I/O L37P_7 VREF_7	I/O	I/O	I/O L51N_7 ◆	VCCINT	GND	GND	GND	GND	GND

Figure 57: FG1156 Package Footprint (Top View)

DS099-4_14a_072903

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17
Bank 6	V	I/O L40P_6 VREF_6	I/O L40N_6	I/O L39P_6	I/O L39N_6	I/O L38P_6	I/O L38N_6	I/O L52P_6	I/O L52N_6	I/O	I/O L49P_6 ◆	VCCINT	GND	GND	GND	GND	GND
	W	GND	I/O L37P_6	I/O L37N_6	VCCO_6	GND	I/O L36P_6	I/O L36N_6	VCCAUX	GND	I/O L35P_6 ◆	VCCO_6	VCCINT	GND	GND	GND	GND
	Y	I/O L34P_6	I/O L34N_6 VREF_6	I/O L33P_6	I/O L33N_6	VCCAUX	I/O L48P_6	I/O L48N_6	VCCO_6	I/O L35N_6	I/O L32P_6	I/O L32N_6	VCCO_6	VCCINT	GND	GND	GND
	A	I/O L31P_6	I/O L31N_6	I/O L30P_6	I/O L30N_6	I/O L29P_6	I/O L29N_6	I/O L28P_6	I/O L28N_6 ◆	I/O L46P_6 ◆	I/O L46N_6 ◆	I/O L27P_6	VCCO_6	VCCINT	GND	GND	GND
	A	GND	VCCO_6	I/O L26P_6	I/O L26N_6	GND	VCCO_6	I/O L25P_6	I/O L25N_6	GND	I/O L24P_6	I/O L27N_6	VCCO_6	VCCINT	VCCINT	VCCINT	VCCINT
	C	I/O L23P_6	I/O L23N_6	I/O L45P_6	I/O L45N_6	I/O L22P_6	I/O L22N_6	I/O L21P_6	I/O L21N_6	I/O L24N_6 VREF_6	I/O L20P_6	I/O L20N_6	VCCINT	VCCO_5	VCCO_5	VCCO_5	VCCO_5
	D	I/O L19P_6	I/O L19N_6	GND	VCCO_6	VCCAUX	I/O L44P_6 ◆	I/O L44N_6 ◆	VCCO_6	I/O L17P_6 VREF_6	I/O L17N_6	I/O	I/O ◆	I/O L16P_5	I/O	I/O	I/O
	E	I/O L16P_6	I/O L16N_6	I/O L15P_6	I/O L15N_6	I/O L14P_6	I/O L14N_6	I/O L13P_6 VREF_6	I/O L13N_6	I/O L12P_6	GND	I/O L39P_5 ◆	I/O L12P_5	I/O L16N_5	I/O	I/O L23P_5	I/O L29P_5 VREF_5
	F	GND	I/O L11P_6	I/O L11N_6	I/O L10P_6	GND	I/O L09P_6	I/O L09N_6 VREF_6	I/O L12N_6	I/O	I/O L07P_5 ◆	I/O L39N_5 ◆	I/O L12N_5	GND	I/O L19P_5 VREF_5	I/O L23N_5	GND
	G	I/O L08P_6	I/O L08N_6	VCCO_6	I/O L10N_6	I/O L07P_6	I/O L07N_6	VCCO_6	M2	I/O	I/O L07N_5	VCCO_5	I/O	I/O L17P_5	I/O L19N_5	VCCO_5	VCCAUX
	H	I/O	I/O	I/O L41P_6 ◆	I/O L41N_6 ◆	I/O L06P_6	I/O L06N_6	GND	VCCO_5	I/O L37P_5	I/O L08P_5	I/O L40P_5 ◆	I/O L13P_5	I/O L17N_5	I/O L20P_5	I/O L24P_5	I/O L27P_5
	J	I/O L05P_6	I/O L05N_6	I/O L04P_6	I/O L04N_6	VCCAUX	I/O	I/O L06P_5	I/O VREF_5	I/O L37N_5	I/O L08N_5	I/O L40N_5 ◆	I/O L13N_5	VCCO_5	I/O L20N_5	I/O L24N_5	I/O L27N_5 VREF_5
	K	GND	I/O L03P_6	I/O L03N_6 VREF_6	M1	GND	VCCAUX	I/O L06N_5	I/O L35P_5	GND	I/O	VCCAUX	I/O L14P_5	GND	I/O	VCCAUX	I/O L31P_5 D5
	L	I/O L02P_6	I/O L02N_6	VCCO_6	M0	I/O VREF_5	I/O L04P_5	I/O L33P_5 ◆	I/O L35N_5	I/O L38P_5	I/O L09P_5	VCCO_5	I/O L14N_5	I/O L18P_5	I/O L21P_5	I/O L25P_5	VCCO_5
	M	I/O L01P_6 VRN_6	I/O L01N_6 VRP_6	GND	VCCO_5	I/O L03P_5	I/O L04N_5	I/O L33N_5 ◆	VCCO_5	I/O L38N_5	I/O L09N_5	GND	I/O	I/O L18N_5	I/O L21N_5	I/O L25N_5	I/O L28P_5 D7
	N	GND	GND	I/O L01P_5 CS_B	I/O L02P_5	I/O L03N_5	I/O L05P_5	I/O L34P_5 ◆	I/O L36P_5	I/O	I/O L10P_5 VRN_5	I/O L11P_5	I/O L15P_5	VCCO_5	I/O L22P_5	I/O L26P_5	I/O L28N_5 D6
	P	GND	GND	I/O L01N_5 RDWR_B	I/O L02N_5	GND	I/O L05N_5	I/O L34N_5 ◆	I/O L36N_5	GND	I/O L10N_5 VRP_5	I/O L11N_5 VREF_5	I/O L15N_5	GND	I/O L22N_5	I/O L26N_5	GND
Bank 5																	

DS099-4_14c_072503

Bottom Left Corner of
FG1156 Package
(Top View)

Figure 59: FG1156 Package Footprint (Top View) Continued